

ISSUE CLASSIFICATION	
Class	Subclass

PATENT NUMBER

**U.S. UTILITY Patent Application**

Q.I.P.E. <i>ml</i>	PATENT DATE
SCANNED <i>Q20</i> <i>aa</i> <i>ml</i>	

APPLICATION NO. 09/834014	CONT/PRIOR D	CLASS <del>438</del> 257	SUBCLASS 703	ART UNIT <del>2812</del> 2826	EXAMINER A. DUTAR
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APPLICANTS Scott Jacobs

TITLE Microelectronic packages including thin film metal and dielectric adhesive layer having conductive vias therein

PTO-2040  
12/89

[illegible]

<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>	<b>DRAWINGS</b>			<b>CLAIMS ALLOWED</b>	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for C.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				<b>NOTICE OF ALLOWANCE MAILED</b>	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____ _____ _____					
				<b>ISSUE FEE</b>	
				Amount Due	Date Paid
<input type="checkbox"/> The term of _____ months of this patent have been disclaimed.				<b>ISSUE BATCH NUMBER</b>	

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